

Date: 12/18/02

12-27-2002

Patent and Trademark Office  
IBM Docket No.:EI-2-02-001

To the Assistant Commissioner For P

ents or copy thereof.

1. Name of conveying party(ies):  
James W. Fuller, Jr., John M. Lauffer, Voya R. Markovich

102323620

address of receiving party(ies):

Additional names of conveying party(ies) attached?

☐ Yes ☒ No

3. Nature of Conveyance

☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other

Execution Date: 12/18/02

Name: Endicott Interconnect Technologies, Inc.Street Address: 1701 North StreetCity EndicottState New York Zip 13760

Additional name(s) &amp; address(es) attached?

☐ Yes ☒ NoJ1033 U.S. PTO  
10/322527  
12/19/02

4. Application number(s) or patent number(s):

Title **CIRCUITIZED SUBSTRATE ASSEMBLY AND METHOD OF MAKING SAME**

If this document is being filed together with a new application, the execution date of the application is 12/18/02

A. Patent Application No(s).

B. Patent No(s).

Additional numbers attached?

☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Lawrence R. Fraley  
IP Law Counsel  
Endicott Interconnect Technologies, Inc.  
FBU/257-2 AA12  
1701 North Street, Endicott, New York 137606. Total number of applications and patents involved: 17. Total fee (37 CVF 3.41): \$40.00☒ Enclosed

## CERTIFICATE OF MAILING UNDER 37 CFR 1.8

I hereby certify that I am depositing the enclosed or attached correspondence with the United States Postal Service as first class mail in an envelope addressed to the Commissioner of Patents and Trademarks, Washington, D.C. 20231 on 12/18/02

Name of person mailing paper.:

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9. Statement and signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Lawrence R. Fraley  
Name of Person Signing

Signature

Date

Registration # 26,885 Tel: 607-755-3207Total number of pages comprising cover sheet:       

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PATENT  
REEL: 013598 FRAME: 0574



**ASSIGNMENT**

Whereas, we

(1) James W. Fuller, Jr.  
County of Broome

City of Endicott  
And State of New York

(2) John M. Lauffer  
County of Tioga

City of Waverly  
And State of New York

(3) Vova R. Markovich  
County of Broome

City of Endwell  
And State of New York

have invented certain improvements in **CIRCUITIZED SUBSTRATE ASSEMBLY AND METHOD OF MAKING SAME**

and have executed, respectively, a United States patent application therefor on

(1) 12/18/2002 , (2) 12/18/2002 , (3) 12/18/2002

And whereas, ENDICOTT INTERCONNECT TECHNOLOGIES, INC., a corporation of New York, having a place of business at Endicott, New York 13760, (hereinafter called EI), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we the above named hereby sell, assign, and transfer to EI, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for protection in the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to EI, its successors and assigns; and we hereby agree that EI may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by EI.

Signed:

at \_\_Endicott, New York\_\_\_\_\_, this 18<sup>th</sup> day of \_\_December\_\_\_\_\_, 2002.

James W. Fuller, Jr.

at \_\_Endicott, New York\_\_\_\_\_, this 18<sup>th</sup> day of \_\_December\_\_\_\_\_, 2002.

John M. Lauffer

at \_\_Endicott, New York\_\_\_\_\_, this 18<sup>th</sup> day of \_\_December\_\_\_\_\_, 2002.

Vova R. Markovich

**PATENT**